

Session Program

28 September 2015 to 2 October 2015



TWEPP 2015 - Topical Workshop on Electronics for Particle Physics

Packaging and interconnects

Lisbon

IST (Instituto Superior Técnico) Alameda Campus Av. Rovisco Pais, 1 1049-001 Lisboa Portugal

Tuesday 29 September

11:35

Packaging and interconnects

Session |

Location: Lisbon, Sala 02.1, IST (Instituto Superior Técnico) Alameda Campus Av. Rovisco Pais, 1 1049-001 Lisboa Portugal |

Convener: Magnus Hansen

11:35-12:00

Construction and Test of the First Belle II SVD Ladder Implementing the Origami Chip-on-Sensor Design

Speaker

Mr Christian Irmeler

12:00